

PATENT ABSTRACTS OF JAPAN

(11)Publication number : 11-176998
(43)Date of publication of application : 02.07.1999

(51)Int.CI.

H01L 23/32
H05K 1/03

(21)Application number : 09-337302
(22)Date of filing : 08.12.1997

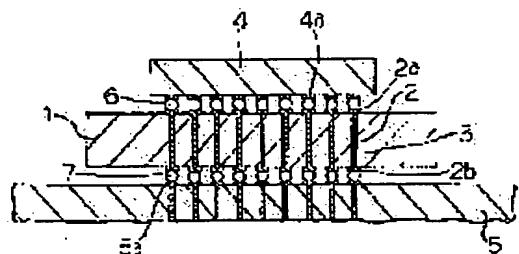
(71)Applicant : KYOCERA CORP
(72)Inventor : YOMO KUNIHIDE

(54) WIRING BOARD

(57)Abstract:

PROBLEM TO BE SOLVED: To prevent a semiconductor device from malfunctioning by a noise which penetrates from an outer electric circuit board of the semiconductor element.

SOLUTION: The board comprises an insulation base 1 having through-holes 3 in the thickness direction and wiring layers 2 having first ends extending to the top face of the base 1, to form upper connection pads 2a connected to electrodes 4a of a semiconductor device 4 and second ends which extend to the bottom face of the base to form lower connection pads 2b connected to wiring conductors 5a of an outer electric circuit board 5. The base 1 is made of SiO₂-Al₂O₃-MgO-MnO-B₂O₃ crystalline glass and contg. at least a magnetic material around the through-holes 3.



LEGAL STATUS

[Date of request for examination] 25.01.2002

[Date of sending the examiner's decision of rejection]

[Kind of final disposal of application other than the examiner's decision of rejection or application converted registration]

[Date of final disposal for application]

[Patent number]

[Date of registration]

[Number of appeal against examiner's decision of rejection]

[Date of requesting appeal against examiner's decision of rejection]

[Date of extinction of right]